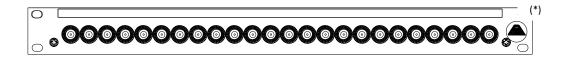




Tech Data

PATCH PANELS

BNC 3G-SDI





Description

- BNC BNC 75 Ω Patch Panel.
- Front side of 2 rows and up to 26 BNC connectors in 2RU.
- Rear side of 2 rows and up to 26 BNC connectors in 2RU.
- According to 3G-SDI SMPTE 424M standard and earlier.
- Clock frequencies from DC to 3 GHz with return loss >10 dB.
- Insulated connector from chassis (Insulation: PTFE (Teflon)).

Applications

Video Patch Panel up to 26 BNC connectors for 3G-SDI signals and earlier.







Tech Data

PATCH PANELS

BNC BNC 3G-SDI

	BNC 3G-SDI	
Physical Characteristics		
BNC Connector	Panel	
	 Panel Frame: Extruded Aluminium. 6063 Alloy. T5 Treatment. Painted Finished: Powder Electrostatic Covering 100-150 μ. Colour: Textured Matte Black. 	
Body: - Material: Zn (Zinc)/ Cu (Copper) - Finish: Ni (Níquel) Inner Conductor: - Material: Cu (Copper) - Finish: Au (Gold) Insulation: PTFE (Teflon)	Label Profile: - Extruded Aluminium. - Painted Finished: • Powder Electrostatic Covering 100-150 μ. • Colour: Textured Matte Black. Label: - Polypropylene 100 μ. - Colour: White. Tie Cable Bar: - Steel bar of F1 calibration and 8 mm. - Painted Finished: • Powder Electrostatic Covering 100-150 μ. • Colour: Textured Matte Black.	







Tech Data

PATCH PANELS

BNC 3G-SDI

Mechanical Characteristics

BNC Connector

Installarion Temperature:

-5º a + 50º C

Working Temperature:

-40º a + 100ºC

Storage Temperature:

-40º a + 100ºC

Electrical Characteristics

BNC Connector

Frequency Response:

0.3 - 3.000 MHz

Impedance:

75 Ω.

Current:

- Measured:

3.5 A a 10 º €

- Calculated:

4.5 A a 20 ºC

Transference Impedance:

 $n/a m\Omega/m = 5-30MHz$

 $n/a m\Omega/item = 5-30MHz$

Shielding Effectiveness (@30-82 MHz):

65 Db

Internal Resistance of Connector (@ 1 A DC):

 $0.9 \,\mathrm{m}\Omega$

Insulation Resistance (@500 V DC):

>200 GΩ

Dielectric Strength (Voltaje de Ensayo DC):

4 KV

Intermodulation (3º Orden (@ 2X0.5 W)):

- IM3:
 - -152 dBc
- IP3:
 - + 102 dBm







Tech Data

PATCH PANELS

BNC 3G-SDI

Return Loss		
(IEC 61169-1) Analyzer RF HP 8714 C		
Frequency	Better than	Typical
0.3 – 500 MHz	-37 dB	-39.9 dB
500 – 860 MHz	-32 dB	-34.6 dB
860 – 1000 MHz	-30 dB	-33.3 dB
1000 – 1750 MHz	-27 dB	-30.0 dB
1750 – 2150 MHz	-26 dB	-28.8 dB
2150 – 3000 MHz	-25 dB	-27.7 dB
Max. Insertion Loss		
Frequency	Better than	Typical
0.3 – 500 MHz	-0.08 dB	-0.03 dB
500 – 860 MHz	-0.08 dB	-0.03 dB
860 – 1000 MHz	-0.08 dB	-0.03 dB
1000 – 1750 MHz	-0.10 dB	-0.05 dB
1750 – 2150 MHz	-0.11 dB	-0.06 dB
2150 – 3000 MHz	-0.17 dB	-0.12 dB

Normativa

- SMPTE 424-2006 (and earlier): This Standard defines a bit-serial data structure for 3GB/s component digital signals or packetized data.
- •IEC 60169-8 amendment 2, Annex A: This Standard defines a 75 Ω BNC connector which can use at frequencies >3.0 GHz and with a Return Loss > 10 dB in 3.0 GHz.
- All test are made with calibrated tools according to this certification: ISO 9001 (ISO 9001:2000/ISO 14001).





Tech Data

PATCH PANELS

BNC 3G-SDI



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For possible changes due to continuous product improvements; Pínanson S.L. reserves the right to change the showed data in this document without notice. The data presented here correspond to the time it was compiled.